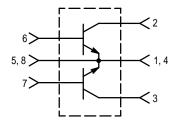
The RF Line NPN Silicon Push-Pull RF Power Transistor

... designed primarily for wideband large-signal output and driver amplifier stages in the 30 to 500 MHz frequency range.

- Specified 28 Volt, 500 MHz Characteristics —
 Output Power = 100 W
 Typical Gain = 9.5 dB (Class AB); 8.5 dB (Class C)
 Efficiency = 55% (Typ)
- Built-In Input Impedance Matching Networks for Broadband Operation
- Push-Pull Configuration Reduces Even Numbered Harmonics
- Gold Metallization System for High Reliability
- 100% Tested for Load Mismatch
- Circuit board photomaster available upon request by contacting RF Tactical Marketing in Phoenix, AZ.

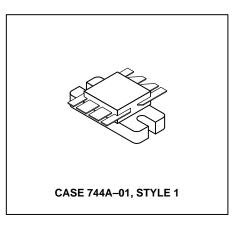


The MRF393 is two transistors in a single package with separate base and collector leads and emitters common. This arrangement provides the designer with a space saving device capable of operation in a push–pull configuration.

PUSH-PULL TRANSISTORS

MRF393

100 W, 30 to 500 MHz CONTROLLED "Q" BROADBAND PUSH-PULL RF POWER TRANSISTOR NPN SILICON



MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	VCEO	30	Vdc
Collector–Base Voltage	Base Voltage V _{CBO}		Vdc
Emitter–Base Voltage	V _{EBO}	4.0	Vdc
Collector Current — Continuous	IC	16	Adc
Total Device Dissipation @ T _C = 25°C (1) Derate above 25°C	PD	270 1.54	Watts W/°C
Storage Temperature Range	T _{stg}	-65 to +150	°C
Junction Temperature	TJ	200	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	0.65	°C/W

NOTE:

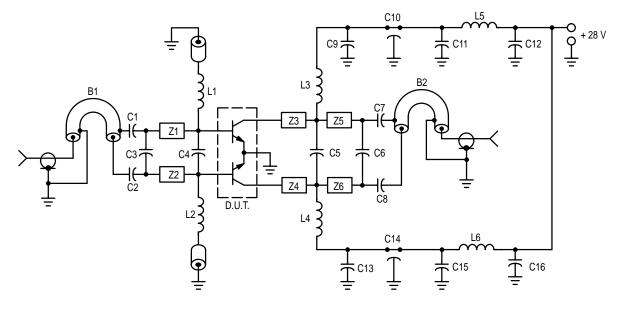
1. This device is designed for RF operation. The total device dissipation rating applies only when the device is operated as an RF push–pull amplifier.

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted.)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS (1)	•		•	•	•
Collector–Emitter Breakdown Voltage (I _C = 50 mAdc, I _B = 0)	V _(BR) CEO	30	_	_	Vdc
Collector–Emitter Breakdown Voltage (I _C = 50 mAdc, V _{BE} = 0)	V(BR)CES	60	_	_	Vdc
Emitter-Base Breakdown Voltage (I _E = 5.0 mAdc, I _C = 0)	V(BR)EBO	4.0	_	_	Vdc
Collector Cutoff Current (V _{CB} = 30 Vdc, I _E = 0)	ICBO	_	_	5.0	mAdc
ON CHARACTERISTICS (1)	•		•	•	•
DC Current Gain (I _C = 1.0 Adc, V _{CE} = 5.0 Vdc)	hFE	20	_	100	_
DYNAMIC CHARACTERISTICS (1)	•				
Output Capacitance (V _{CB} = 28 Vdc, I _E = 0, f = 1.0 MHz)	C _{ob}	40	75	95	pF
FUNCTIONAL TESTS (2) — See Figure 1	•				
Common–Emitter Amplifier Power Gain (VCC = 28 Vdc, P _{out} = 100 W, f = 500 MHz)	G _{pe}	7.5	8.5	_	dB
Collector Efficiency (V _{CC} = 28 Vdc, P _{out} = 100 W, f = 500 MHz)	η	50	55	_	%
Load Mismatch (V _{CC} = 28 Vdc, P _{out} = 100 W, f = 500 MHz, VSWR = 30:1, all phase angles)	Ψ	N	No Degradation in Output Power		

NOTES:

- 1. Each transistor chip measured separately.
- 2. Both transistor chips operating in push–pull amplifier.



C1, C2, C7, C8 — 240 pF 100 mil Chip Cap

C3 — 15 pF 100 mil Chip Cap

C4 — 24 pF 100 mil Chip Cap

C5 — 33 pF 100 mil Chip Cap

C6 — 12 pF 100 mil Chip Cap

C9, C13 — 1000 pF 100 mil Chip Cap

C10, C14 — 680 pF Feedthru Cap

C11, C15 — 0.1 μF Ceramic Disc Cap C12, C16 — 50 μF 50 V

L1, L2 — 0.15 μH Molded Choke with Ferrite Bead

L3, L4 — 2-1/2 Turns #20 AWG 0.200" ID

L5, L6 — 3–1/2 Turns #18 AWG 0.200" ID

B1, B2 — Balun 50 Ω Semi Rigid Coax, 86 mil OD, 4" Long

Z1, Z2 — 850 mil Long x 125 mil W. Microstrip

Z3, Z4 — 200 mil Long x 125 mil W. Microstrip

Z5, Z6 — 800 mil Long x 125 mil W. Microstrip

Board Material — 0.0325" Teflon–Fiberglass, ε_{Γ} = 2.56, 1 oz. Copper Clad both sides.

Figure 1. 500 MHz Test Fixture

CLASS C

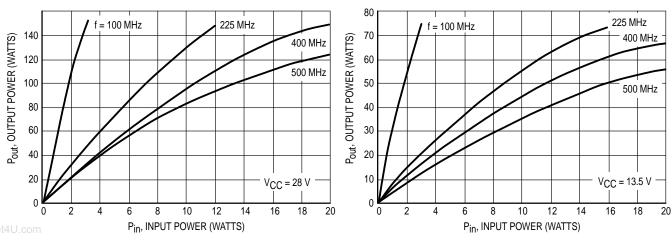


Figure 2. Output Power versus Input Power

Figure 3. Output Power versus Input Power

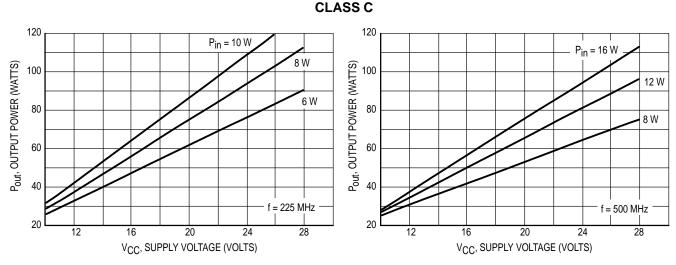


Figure 4. Output Power versus Supply Voltage

Figure 5. Output Power versus Supply Voltage

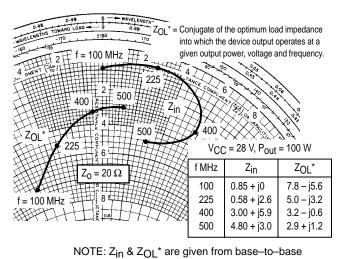


Figure 6. Series Equivalent Input/Output Impedance

and collector-to-collector respectively.

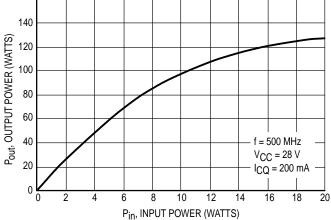
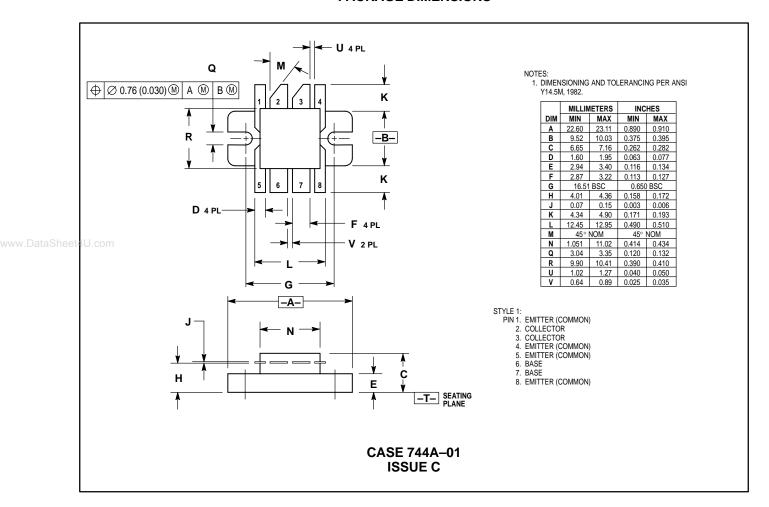


Figure 7. Class AB Output Power versus Input Power

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